

# Bill of Materials

TI DESIGNS

TIDM-TEMPCOMPENSATED-RTC

Description	Value	Designator	Pcs/Unit	Footprint	Manufacturer
SMD,Capacitor,±20%	0.1uF	C6 C7 C50 C51 C52 C131 C151 C152	17	0603	Yageo
SMD,Capacitor,±20%	0.47uF	C53	1	0603	Yageo
SMD,Capacitor,±20%	2.2nF	C48	1	0603	Yageo
SMD,Capacitor,±20%	4.7uF	C54	1	0603	Yageo
SMD,Capacitor,±20%	10uF	C55 C56 C57	3	0805	Yageo
SMD,Capacitor,±20%	1000pF	C153 C154 C211 C232	4	0603	Yageo
SMD,Capacitor,±10%	180pF	C132 C133	2	0603	Yageo
SMD,Capacitor,±10%	15nF	C78 C81 C84	3	0603	Yageo
SMD,Capacitor,±10%	15pF	C47 C49	2	0603	Yageo
SMD,Capacitor,±10%	22pF	C322	1	0603	Yageo
SMD,Capacitor,±10%	47pF	C76 C77 C79 C80 C82 C83	6	0603	Yageo
SMD,Capacitor,±10%	68pF	C281-C314	34	0603	Yageo
SMD,Resistor,±5%	0 ohm	R283	1	0603	Yageo
SMD,Resistor,±5%	10k ohm	R15 R34 R35 R37 R39 R41 R74 R298	8	0603	Yageo
SMD,Resistor,±1%	1k ohm	R94 R96 R98 R99 R101 R102	6	0603	Yageo
SMD,Resistor,±5%	1k ohm	R14 R171 R174 R206 R207 R213 R215 R216 R218 R343 R346 R347 R412	13	0603	Yageo
SMD,Resistor,±5%	2k ohm	R16 R29 R31	3	0603	Yageo
SMD,Resistor,±5%	20k ohm	R241	1	0603	Yageo
SMD,Resistor,±5%	3k ohm	R13 R30 R32	3	0603	Yageo
SMD,Resistor,±5%	33k ohm	R17 R18	2	0603	Yageo
SMD,Resistor,±5%	300 ohm	R341 R345	2	0603	Yageo
SMD,Resistor,±5%	100k ohm	R201 R202	2	0603	Yageo
SMD,Resistor,±1%	100 ohm	R95	1	0603	Yageo
SMD,Resistor,±5%	100 ohm	R24 R413	2	0603	Yageo
SMD,Resistor,±1%	470 ohm	R11	1	0603	Yageo
SMD,Resistor,±5%	4.7k ohm	R12 R25 R26 R33 R36 R38 R40 R177 R342	11	0603	Yageo
SMD,Resistor,±5%	47k ohm	R72	1	0603	Yageo
SMD,Resistor,±5%	5.1k ohm	R211 R212 R214 R217 R219 R220 R300	7	0603	Yageo
SMD,Resistor,±1%	10 ohm	R100	1	0603	Yageo
SMD,Resistor,±5%	10 ohm	R73	1	0603	Yageo
SMD,Resistor,±5%	7.5k ohm	R151 R152	2	0603	Yageo

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SMD,Resistor,±5%	1M ohm	R203 R265 R281 R282	4	0603	Yageo
SMD,Resistor,±5%	300k ohm	R261 R262 R263 R264	4	0805	Yageo
SMD,Resistor,±1%	150k ohm	R92 R93	2	1206	Yageo
SMD,Resistor,±1%	240k ohm	R91	1	1206	Yageo
SMD,Diode	IN4148	D92 D94 D95 D96	4	IN4148-SMT	
SMD,MCU	MSP430F6736	U26	1	TQFP100-0.26	Texas Instruments
SMD,RS485	SN65HVD3082E	U5	1	SOIC8	Texas Instruments
SMD,EEPROM	24LC256B-I/SN	U41	1	SOIC8	
SMD,Transistors,NPN	3904	Q3 Q4 Q5 Q6 Q7 Q8 Q36 Q51 Q53 Q55	12	3904_3906	
SMD,Transistors,PNP	3906	Q9 Q10 Q37 Q52 Q54 Q126	6	3904_3906	
SMD,LDO	78L05	U88	1	SOT-89	Texas Instruments
SMD,LDO	HT7550	U89	1	SOT-89	HT
SMD,Rectifier Diode	M7	D81 D91	2	IN5817-SMT	
SMD,Rectifier Bridge	MB6S	V2	1	MBS-1	
SMD,NTC	10k ohm	R242	1	0805	Exsense
SMD,Bead	STBL-120	Z6 Z7 Z8 Z9	4	0805	
Through-hole, LED	RED LED-Φ5	D113 D114 D115	3	LED	
Through-hole, Crystal,12.5p-5ppm	32.768kHz VT200	G1	1	G-32.768	SEIKO
Through-hole, LCD	LCD-JY09484	LCD1	1	LCD-JY09484A	HEBEI JIYA
Through-hole, Voltage Transformer	JS28D20-18A	T1	1	TRANS-TD28-18-3	QINGZHOU JINSHUN
Through-hole, Back Light Panel	C01W-7131-6	D111	1	BG-ST-7131	SHENZHEN SAITE
Through-hole, lithium battery	ER14250AH	BAT3	1	B-CR1/2AA	YIWEI
Through-hole, Button	6*6*4.3	K1 K2	2	RESET	
Through-hole, Micro-Switch	KF-508	K3	1	KFT-5.8	
Through-hole, ESAM	ESAM2605	U131	1	DIP-8	CSG
Through-hole, Electrolytic Capacitor	100uF/35V	C221	1	D*D*F 6.3*0.5*2.50	
Through-hole, Electrolytic Capacitor	220uF/16V	C224	1	D*D*F 6.3*0.5*2.5	
Through-hole, Electrolytic Capacitor	470uF/16V	C229	1	D*D*F 8*0.6*3.5	
Through-hole, Electrolytic Capacitor	1000uF/35V	C225	1	D*D*F 12.5*0.6*5.0	
Through-hole, Zener diode	1N4744A	ZD23	1	DO41-UP	
Through-hole, Piezoresistor	20K681	RV31	1	RV20K681	
Through-hole, Optocoupler	PC817C	U2 U3 U51 U52 U79	5	DIP-4	
Through-hole, Bead	B62	Z24 Z25	2	B62A	
Through-hole, Thermistor	MZ4-250	PT7	1	PTC-120/120-35MA	
Through-hole, Thermistor	MZ6-51R	RT3	1	PTC-120/120-35MA	
Through-hole, TVS	P6KE6.8CA	TV1	1	TVSUP	
Through-hole, TVS	P6KE22CA	TV33	1	TVSUP	
Through-hole, Infrared Reader	HM238	U6	1	TSOP1838	
Through-hole, Infrared Sender	AT205B	D5	1	LED-5	
Emeter Case		201Type 10 (60) A	1		QUANSHENG
Relay		GRT508FA 250uΩ	1		GELEITE
Current transformer		10 (60) /5MA	1		
PCB Board			1		

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